



PMEG2015EPK

20 V, 1.5 A low VF Schottky barrier rectifier

30 September 2025

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage $V_F \leq 420$ mV
- Low reverse current
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- LED backlight for mobile application
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

4. Quick reference data

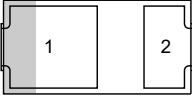
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta < 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 100$ °C	[1]	-	-	1.5	A
		$\delta < 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 140$ °C		-	-	1.5	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	20	V
V_F	forward voltage	$I_F = 1.5$ A; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C		-	375	420	mV
I_R	reverse current	$V_R = 10$ V; $T_j = 25$ °C		-	70	350	μ A
t_{rr}	reverse recovery time	$I_F = 0.5$ A; $I_R = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C		-	5	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 Transparent top view DFN1608D-2 (SOD1608)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

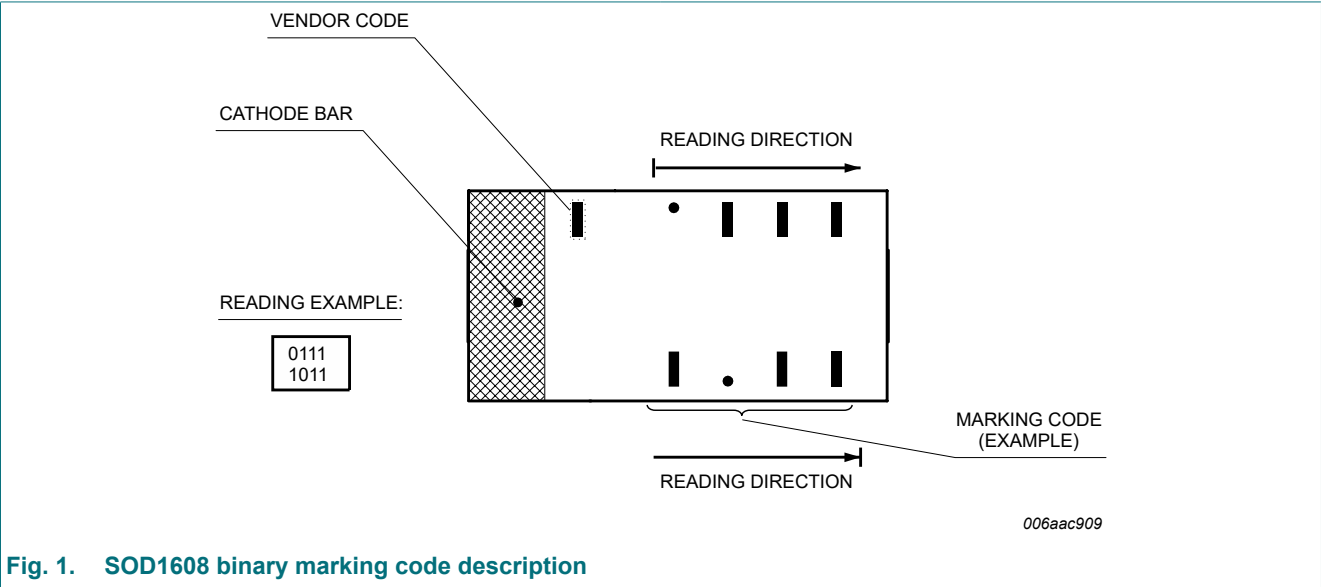
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2015EPK	DFN1608D-2	plastic, leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.94 mm pitch; 1.6 mm x 0.8 mm x 0.37 mm body	SOD1608

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2015EPK	1100 0000



8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	20	V
I_F	forward current	$T_{sp} \leq 135\text{ }^{\circ}\text{C}$		-	2.1	A
$I_{F(AV)}$	average forward current	$\delta < 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 100\text{ }^{\circ}\text{C}$	[1]	-	1.5	A
		$\delta < 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 140\text{ }^{\circ}\text{C}$		-	1.5	A
I_{FRM}	repetitive peak forward current	$t_p = 1\text{ ms}$; $\delta = 0.25$		-	4	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; square wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$		-	5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[2] [3]	-	415	mW
			[4] [3]	-	895	mW
			[1] [3]	-	1565	mW
T_j	junction temperature			-	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	150	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	150	$^{\circ}\text{C}$

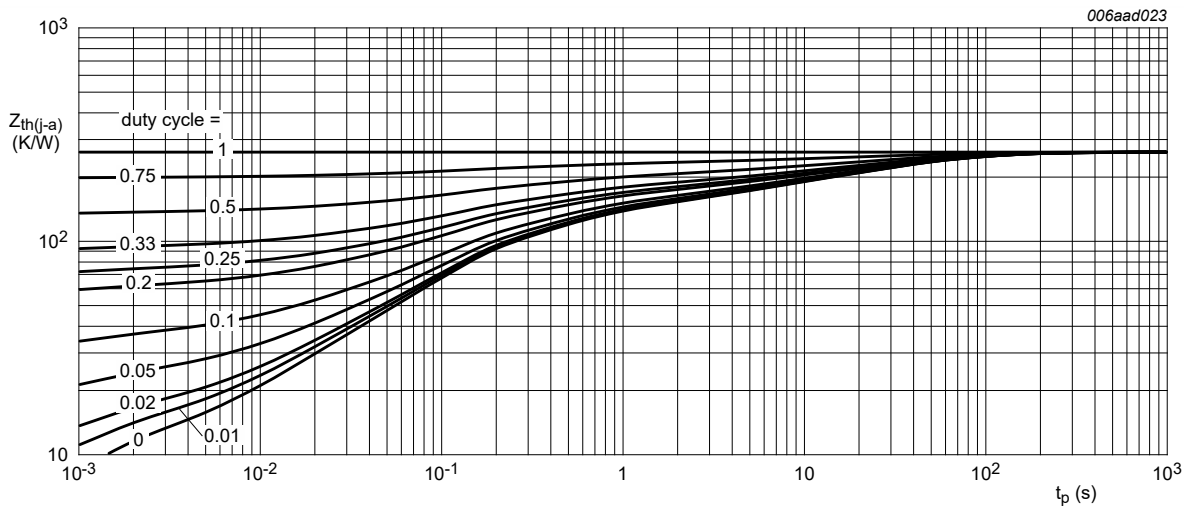
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

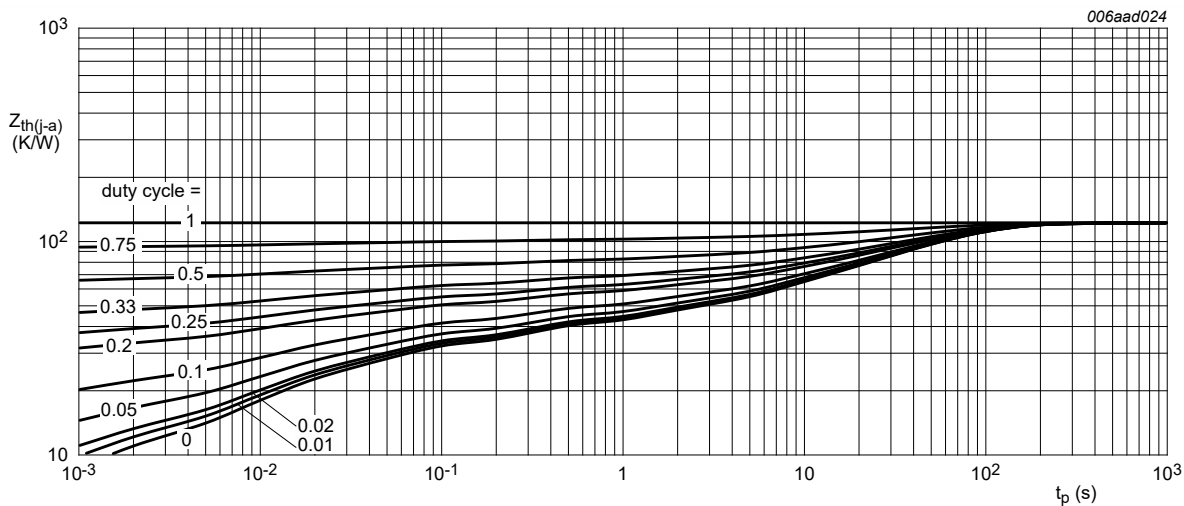
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	300	K/W
			[1] [4] [3]	-	-	140	K/W
			[1] [5] [3]	-	-	80	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	20	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .
 [5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.
 [6] Soldering point of cathode tab.



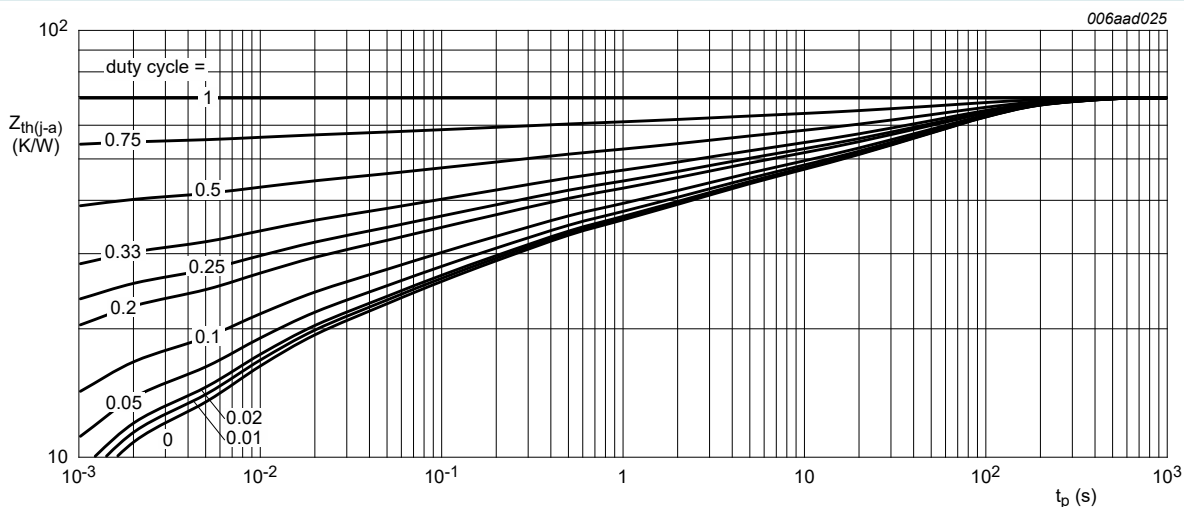
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



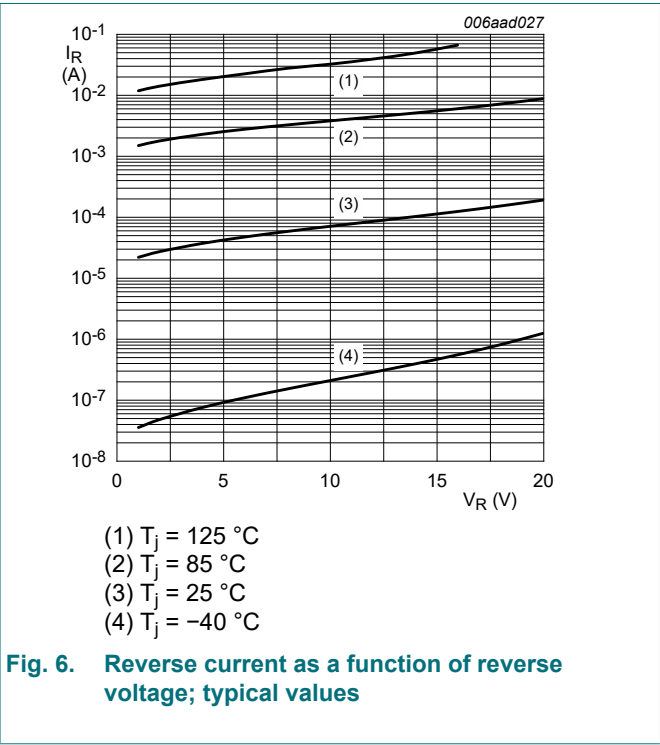
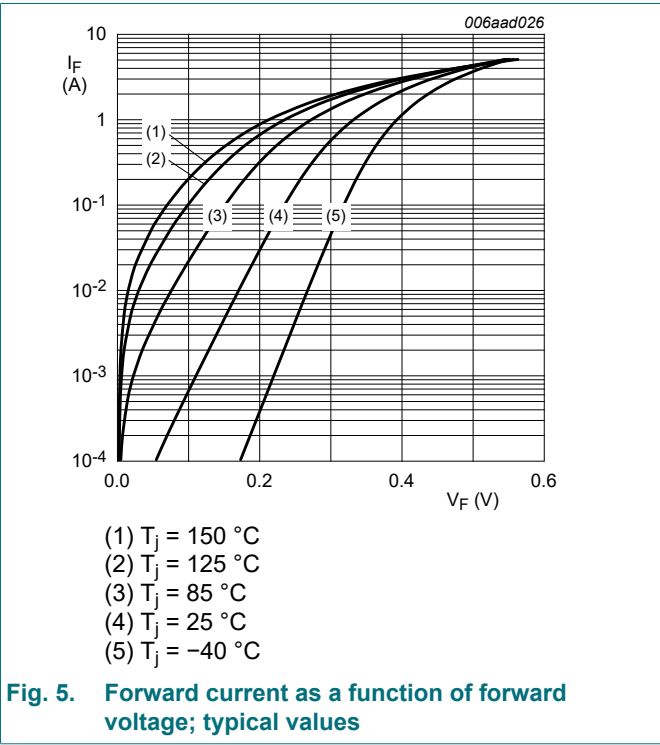
Ceramic PCB, Al₂O₃, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	230	260	mV
		I _F = 500 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	290	330	mV
		I _F = 1 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	330	380	mV
		I _F = 1.5 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	375	420	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	-	70	350	μA
		V _R = 20 V; T _j = 25 °C	-	220	900	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	105	120	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C	-	40	50	pF
t _{rr}	reverse recovery time	I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C	-	5	-	ns
V _{FRM}	peak forward recovery voltage	I _F = 0.5 A; dI _F /dt = 20 A/μs; T _j = 25 °C	-	320	-	mV



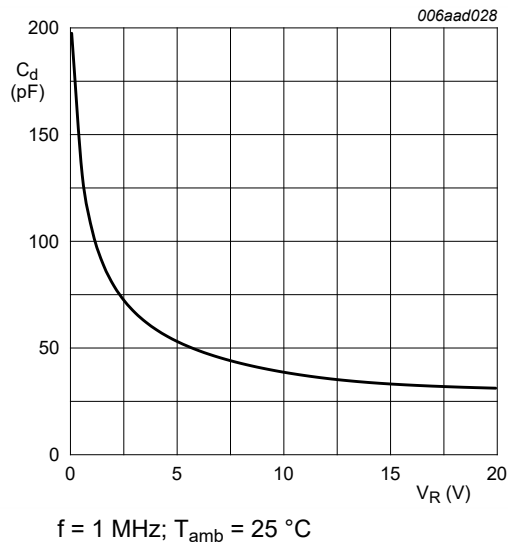


Fig. 7. Diode capacitance as a function of reverse voltage; typical values

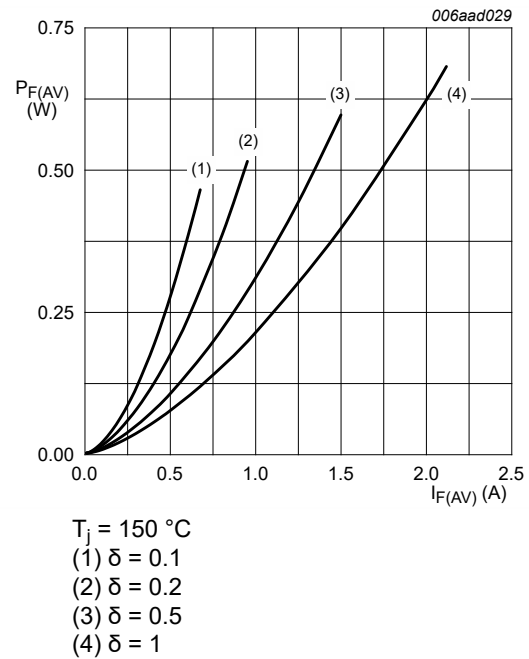


Fig. 8. Average forward power dissipation as a function of average forward current; typical values

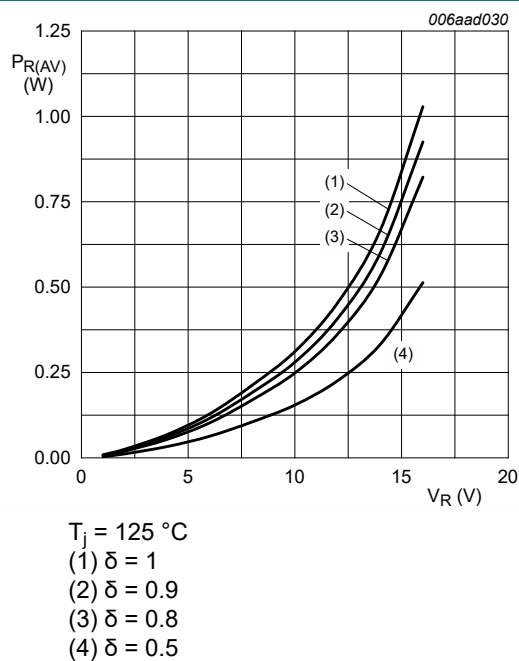


Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

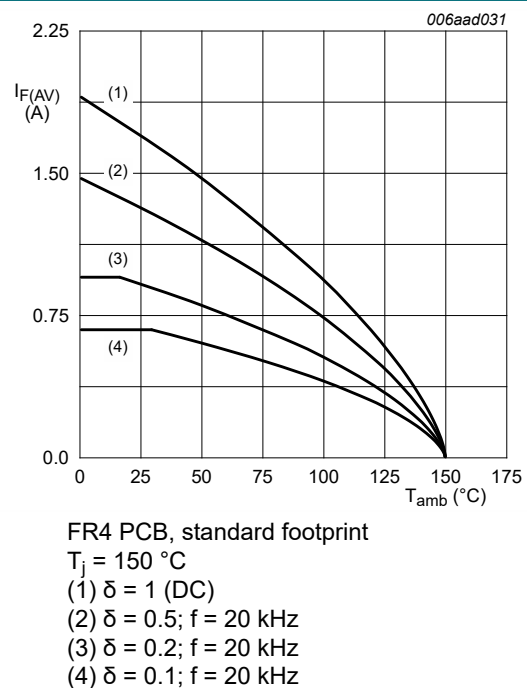
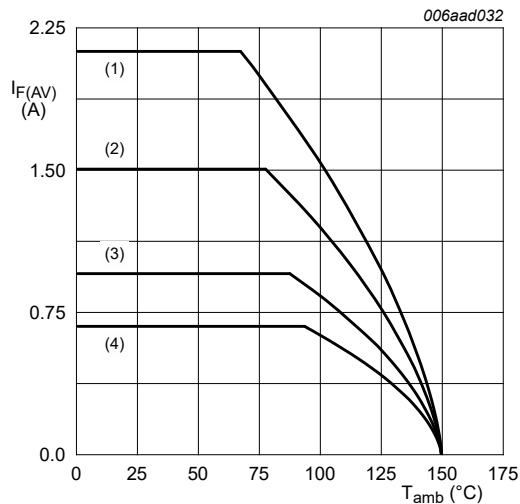
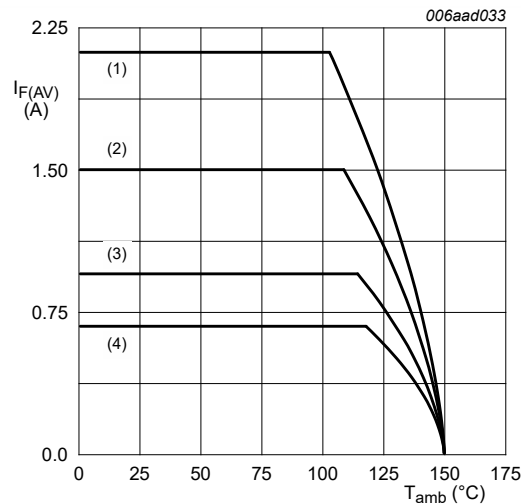


Fig. 10. Average forward current as a function of ambient temperature; typical values



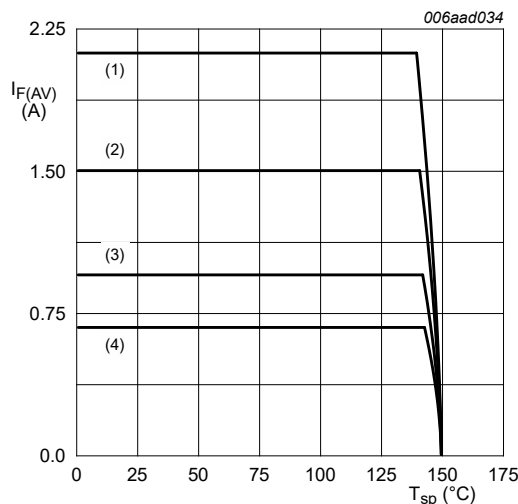
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 13. Average forward current as a function of solder point temperature; typical values

11. Test information

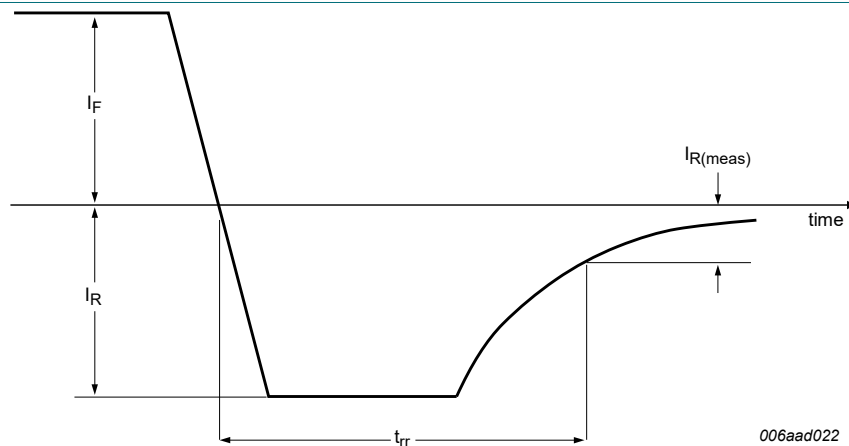


Fig. 14. Reverse recovery definition

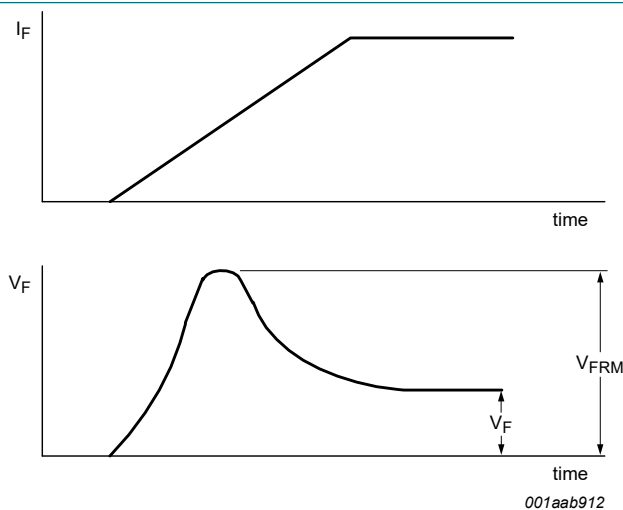


Fig. 15. Forward recovery definition

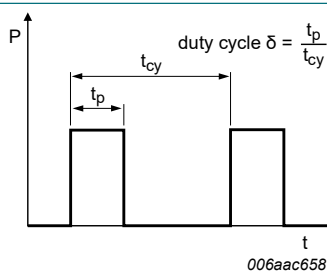


Fig. 16. Duty cycle definition

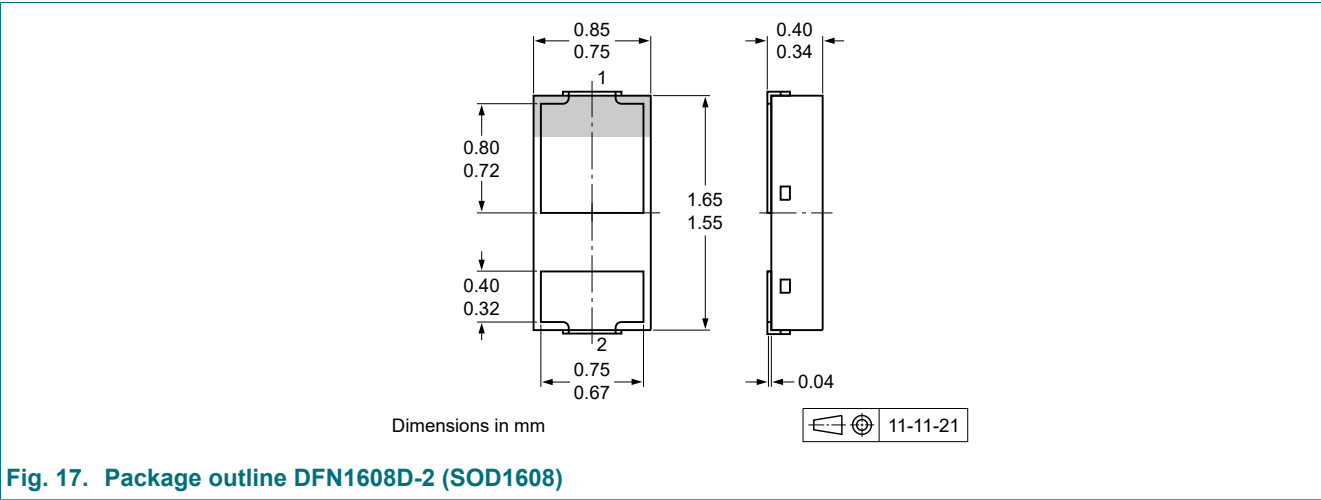
The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

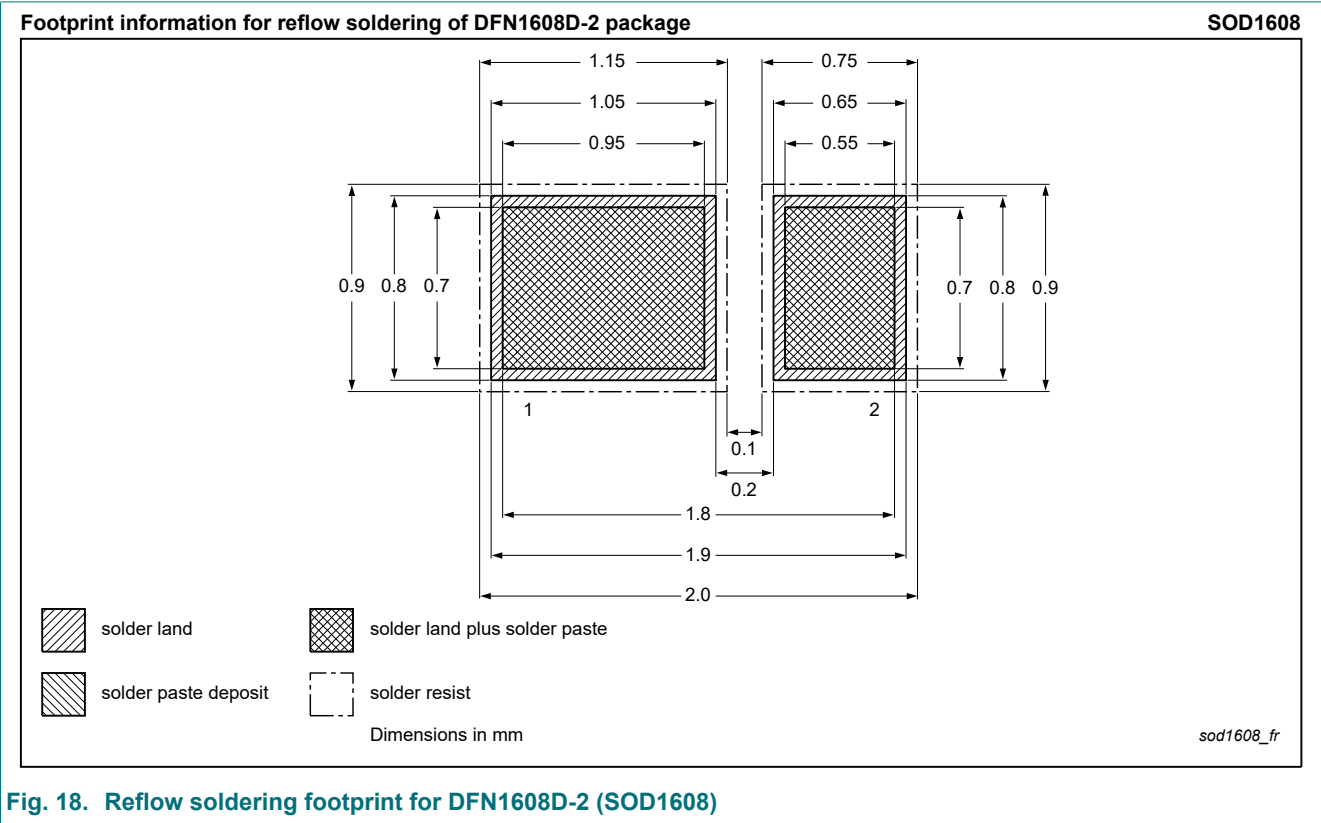
$$I_{RMS} = I_{F(AV)} \text{ at DC,}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current.}$$

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2015EPK v.3	20230930	Product data sheet	-	PMEG2015EPK v.2
Modifications:	Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).			
PMEG2015EPK v.2	20230921	Product data sheet	-	PMEG2015EPK v.1
PMEG2015EPK v.1	20120306	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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